

**Notice of References Cited**

Application/Control No.

09/988,740

Applicant(s)/Patent Under  
Reexamination  
PIHLAJA, PEKKA JUHANA

Examiner

Alonzo Chambliss

Art Unit

2827

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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

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	W	" Integrated Module Heat Exchanger ", April 1978, IBM Technical Disclosure Bulletin, page 4498.
	X	" Conduction Cooling Module with a Variable Resistance ", November 1978, IBM Technical Disclosure Bulletin, page 2434.

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